Specifications Specifications Essentials Essentials Performance Status Memory Specifications Launch Date **Expansion Options** Processor Number Package Specifications Advanced Technologies Intel® Smart Cache Intel® Data Protection Intel® QPI Speed Technology # of QPI Links Intel® Platform Protection Technology Instruction Set Compatible Products Product Images Lithography Ordering / sSpecs /

TDP

Memory Specifications

Steppings

Launched 01'12 E5-2630L 15 MB 7.2 GT/s 2 64-bit Instruction Set Extensions AVX Q No Embedded Options Available 32 nm Scalability 25 Only VID Voltage Range 0.60V-1.35V Recommended Customer Price TRAY: \$662.00 Link Datasheet Performance # of Cores 6 # of Threads 12 Processor Base Frequency 2 GHz Max Turbo Frequency 2,5 GHz

60 W

Related Products Intel® Xeon® Processor E5 Family Intel® Xeon® Processor E5-2600 Product Family Products formerly Sandy Bridge EP Quick Links Export Full Specifications > Search Distributors > Software Downloads > Support Overview > Search all of intel.com > PCN/MDDS Information SROKM 919077; PCN | MDDS SROH1 917888: PCN | MDDS

Max Memory Size (dependent on memory type) 384 GB Memory Types DDR3 800/1066/1333 Max # of Memory Channels 42.6 GB/s Max Memory Bandwidth Q Yes ECC Memory Supported # Expansion Options 3.0 PCI Express Revision 40 Max # of PCI Express Lanes Package Specifications Max CPU Configuration 2 69.8°C CASE Package Size 52.5mm x 45.0mm Sockets Supported FCLGA2011 Low Halogen Options Available See MDDS Advanced Technologies Intel® Turbo Boost Technology * 2.0 Intel® vPro Technology * Q Yes Q Yes Intel® Hyper-Threading Technology * Intel® Virtualization Technology (VT-x) * Intel® Virtualization Technology for Directed I/O Q (VT-d) * Intel® VT-x with Extended Page Tables (EPT) * Q Yes Q Yes Intel® 64 * Idle States Q Enhanced Intel SpeedStep® Technology Q Yes Intel® Demand Based Switching Thermal Monitoring Technologies Intel® Flex Memory Access No Intel® Identity Protection Technology * No Intel® Data Protection Technology Q Yes AES New Instructions Intel® Platform Protection Technology Trusted Execution Technology *

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Refer to Datasheet for formal definitions of product properties and features.

"Announced" SKUs are not yet available. Please refer to the Launch Date fo

"Announced" SKUs are not yet available. Please refer to the Launch Date for market availability.

Some products can support AES New Instructions with a Processor Configuration update, in particular, i7-2630QM/i7-2635QM, i7-2670QM/i7-2675QM, i5-2430M/i5-2435M, i5-2410M/i5-2415M. Please contact

Execute Disable Bit *

OEM for the BIOS that includes the latest Processor configuration update.

† This feature may not be available on all computing systems. Please check with the system vendor to determine if your system delivers this feature, or reference the system specifications (motherboard, processor, chipset, power supply, HDD, graphics controller, memory, BIOS, drivers, virtual machine monitor-VMM, platform software, and/or operating system) for feature compatibility. Functionality,

performance, and other benefits of this feature may vary depending on system configuration.
"Conflict free" and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum,

Conflict free "and "conflict-free" means "DRC conflict free", which is defined by the U.S. Securities and Exchange Commission rules to mean products that do not contain conflict minerals (tin, tantalum, tungsten and/or gold) that directly or indirectly finance or benefit armed groups in the Democratic Republic of the Congo (DRC) or adjoining countries. Intel also uses the term "conflict-free" in a broader sense to refer to suppliers, supply chains, smelters and refiners whose sources of conflict minerals do not finance conflict in the DRC or adjoining countries. Intel processors manufactured before January 1, 2013 are not confirmed conflict free. The conflict free designation refers only to product manufactured after that date. For Intel Boxed Processors, the conflict free designation refers to the processor only, not to any additional included accessories, such as heatsinks/coolers.

See http://www.intel.com/content/www/us/en/architecture-and-technology/hyper-threading-technology.html?wapkw=hyper+threading for more information including details on which processors support Intel® HT Technology.

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Max Turbo Frequency refers to the maximum single-core processor frequency that can be achieved with Intel® Turbo Boost Technology, See www.intel.com/technology/turboboost/ for more information.

System and Maximum TDP is based on worst case scenarios. Actual TDP may be lower if not all I/Os for chipsets are used.

Low Halogen: Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. Intel components as well as purchased components on the finished assembly meet

JS-709 requirements, and the PCB / substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants and/or PVC may not be better for the environment.

For benchmarking data see http://www.intel.com/performance.

Intel processor numbers are not a measure of performance. Processor numbers differentiate features within each processor family, not across different processor families. See http://www.intel.com/content

/www/us/en/processors/processor-numbers.html for details.

Processors that support 64-bit computing on Intel® architecture require an Intel 64 architecture-enabled BIOS.

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